

The 38th International Symposium on Power Semiconductor Devices and ICs

Las Vegas, Nevada
May 24-28, 2026



ISPSD 2026

2nd Call for Papers
www.ispsd2026.com

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ISPSD is the premier forum for technical discussions in all areas of power semiconductor devices and power integrated circuits, including but not limited to device physics, modeling, design, fabrication, materials, packaging and integration, device reliability, and device/circuit interactions.

ISPSD 2026 will be held in Las Vegas, Nevada at the MGM Grand Las Vegas. Las Vegas, a vibrant and cosmopolitan city, is a top destination for entertainment, dining and vibrant cultural scene.

Conference Submission Tracks:

- **High Voltage Devices (HV):** High voltage silicon based discrete devices (>200V) such as SJ-MOSFETs, IGBTs, thyristors and pn-diodes
- **Low Voltage Devices and Power IC Device Technology (LVT):** Low voltage silicon based discrete power devices ($\leq 200V$) and devices for power ICs of all voltage ranges
- **Power IC Design (ICD):** Circuit design and demonstration using power IC technology platform
- **GaN and Compound Materials:** GaN and nitride-based compound materials (e.g. AlN, GaAs) based power devices, technology and integration, materials, and processing.
- **SiC and Other Materials (SiC):** SiC and other material (e.g. Ga₂O₃, diamond) based power devices, technology and integration, materials, and processing.
- **Module and Packaging Technologies (PK):** System Integration in Package Module and package technology for discrete power devices and power ICs

Abstract Submission

Prospective authors should visit the ISPSD 2026 website: <https://www.ispsd2026.com>

Important Dates:

Jan 12, 2026: **4-pages full paper** submission

March 3, 2026: Author notification

March 12, 2026: Final submission deadline for final paper and copyright filing

Please Note: ISPSD 2026 has changed the paper submission process. Note that a 4-page full paper submission is required. Traditional "Abstract Submission" will NOT be accepted. No late news session.

Template:

<https://www.ieee.org/conferences/publishing/templates.html>

Paper length: Maximum 4 pages

Paper size: US Letter

File format: Adobe PDF (.pdf)

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